

PMP8251 Rev A BOM

4-Jun-13

rev B updates in **bold red**

PMP8251 rev B BOM

to be built on PCB PMP8251A

Qty	Reference	Value	Description	Size	Part Name	MFR
8	C5-6 C10-11 C16-17 C22-23	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	603	C1608X7R1H104K	TDK
1	C1	1.0 uF	Capacitor, Ceramic, 10V, X7R, 10%	603	Std	Std
2	C25-26	1.0uF	Capacitor, Ceramic, 25V, X5R, 10%	603	C1608X5R1E105K	TDK
1	C27	1000pF	Capacitor, Ceramic, 25V, X5R, 10%	603	C1608X5R1E105K	TDK
1	C30	100nF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
2	C29 C31	10uF	Capacitor, Ceramic, 6.3V, X5R, 10%	603	Std	Std
4	C4 C9 C15 C21	1uF	Capacitor, Ceramic, 16V, X7R, 20%	603	Std	Std
1	C2	2.2uF	Capacitor, Ceramic, 6.3V, X5R	603	Std	Std
1	C32	220nF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
1	C28	4.7uF	Capacitor, Ceramic, 6.3V, X5R, 10%	603	C1608X5R0J475K	TDK
4	C7 C12 C19 C24	22uF	Capacitor, Ceramic, 6.3V, X5R, 15%	805	Std	Std
1	C18	DNP	Do Not Populate	805	N/A	N/A
3	C33-35	Open	Capacitor, Ceramic, 6.3V, X5R, 15%	805	Std	Std
4	C3 C8 C13 C20	10uF	Capacitor, Ceramic, 16V, X7R, 15%	1206	STD	STD
1	C14	DNP	Do Not Populate	1206	N/A	N/A
1	J1	PTC36SAAN	Header, 2-pin, 100mil spacing, (36-pin strip)	0.100 x 2	PTC36SAAN	Sullins
1	J13	PTC36SAAN	Header, 2 pin, 100mil spacing, (36-pin strip)	0.100 x 2	PTC36SAAN	Sullins
1	J19	PEC04SAAN	Header, Male 4-pin, 100mil spacing,	0.100 inch x 4	PEC04SAAN	Sullins
1	J9	PEC03DAAN	Header, Male 2x3-pin, 100mil spacing	0.20 inch x 0.30	PEC03DAAN	Sullins
4	L1-4	2.2uH	Inductor, Shielded Drum Core, 4A, 20milliohms	0.300" sq	7447789002	Würth
5	R4-5 R8 R11 R16	100k	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R2 R6 R9 R14	10k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R1	110	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R3 R10	13.7k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R12	22.6k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R7	3.09k	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R13 R15	33.2k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R17	4.12k	Resistor, Chip, 1/16W, 1%	603	Std	Std

PMP8251 Rev A BOM

Qty	Reference	Value	Description	Size	Part Name	MFR
1	R18	4.75k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	U3	REF1112AIDBZ	IC, Shunt Voltage Reference 10ppm/°C, 1µA, 1.25V	SOT23	REF1112AIDBZ	TI
6	J3-4 J6 J8 J10-11	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	J17	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
24	TP1-5 TP7-9 TP11-14 TP16-18 TP21, TP23-24, TP26-31	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP20	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100	5000	Keystone
6	TP6 TP10 TP15 TP19 TP22 TP25	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U8	TPS51206	IC, 2A-Peak Sink/Source DDR Termination Regulator with VTTREF	SON	TPS51206DSQ	TI
4	U2 U4-6	TPS54325PWP	IC, 3-A Switcher W/ Integrated FET	HTSSOP-14	TPS54325PWP	TI
1	U7	TPS74201RGW	IC, 1.5A LDO Linear Regulator w/Programmable Soft start	QFN-20	TPS74201RGW	TI
1	U1	TLV70218	IC, 300mA, Low IQ, Low-Dropout Regulator for Portables	TSOT23-5	TLV70218DBVR	TI

Notes:

**On PCB PMP8251A: VDDQ input to U8 needs to be cut from the 1.8V and jumpered to the 1.5V. See schematic
Jumpering wire should be robust to carry ~1 A with under 5mV of drop.**

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